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JOINT INDUSTRY STANDARD

Requirements for
Soldered Electrical
and Electronic
Assemblies



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IPC J-STD-001G

Requirements for Soldered Electrical and Electronic Assemblies

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Requirements for Soldered Electrical and Electronic Assemblies

1 GENERAL

 **1.1 Scope** This Standard describes materials, methods and acceptance criteria for producing soldered electrical and electronic assemblies. The intent of this document is to rely on process control methodology to ensure consistent quality levels during the manufacture of products. It is not the intent of this Standard to exclude any procedure for component placement or for applying flux and solder used to make the electrical connection.

 **1.2 Purpose** This Standard prescribes material requirements, process requirements, and acceptability requirements for the manufacture of soldered electrical and electronic assemblies. For a more complete understanding of this document's recommendations and requirements, one may use this document in conjunction with IPC-HDBK-001, IPC-AJ-820 and IPC-A-610. Standards may be updated at any time, including with the addition of amendments. The use of an amendment or a newer revision is not automatically required.

1.3 Classification This Standard recognizes that electrical and electronic assemblies are subject to classifications by intended end-item use. Three general end-product classes have been established to reflect differences in manufacturability, complexity, functional performance requirements, and verification (inspection/test) frequency. It should be recognized that there may be overlaps of equipment between classes.

The User, see 1.8.13, is responsible for defining the product class. The product class should be stated in the procurement documentation package.

CLASS 1 General Electronic Products

Includes products suitable for applications where the major requirement is function of the completed assembly.

CLASS 2 Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically the end-use environment would not cause failures.

CLASS 3 High Performance/Harsh Environment Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

1.4 Measurement Units and Applications This Standard uses International System of Units (SI) units per ASTM SI10, IEEE/ASTM SI 10, Section 3 [Imperial English equivalent units are in brackets for convenience]. The SI units used in this Standard are millimeters (mm) [in] for dimensions and dimensional tolerances, Celsius (°C) [°F] for temperature and temperature tolerances, grams (g) [oz] for weight, and lumens (lm) [footcandles] for illuminance.

Note: This Standard uses other SI prefixes (ASTM SI10, Section 3.2) to eliminate leading zeroes (for example, 0.0012 mm becomes 1.2 μm) or as alternative to powers-of-ten (3.6 x 10³ mm becomes 3.6 m).

1.4.1 Verification of Dimensions Actual measurement of specific part mounting and solder fillet dimensions and determination of percentages are not required except for referee purposes. For determining conformance to the specifications in this Standard, round all observed or calculated values "to the nearest unit" in the last right-hand digit used in expressing the specification limit, in accordance with the rounding method of ASTM Practice E29. For example, specifications of 2.5 mm max, 2.50 mm max, or 2.500 mm max, round the measured value to the nearest 0.1 mm, 0.01 mm, or 0.001 mm, respectively, and then compare to the specification number cited.

1.5 Definition of Requirements The words **shall** or **shall not** are used in the text of this document wherever there is a requirement for materials, preparation, process control or acceptance of a soldered connection.